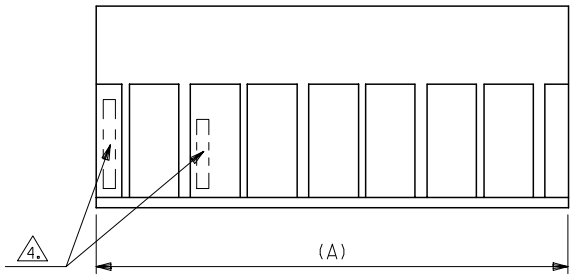
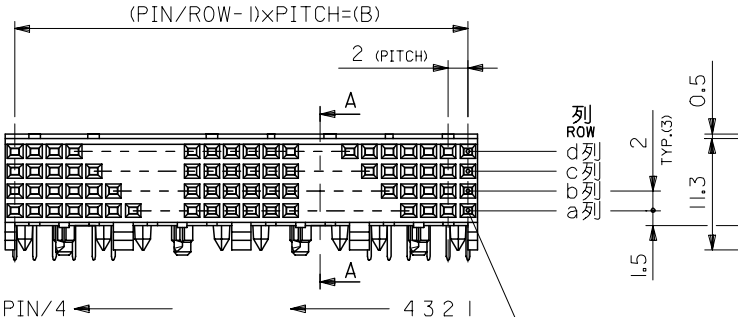
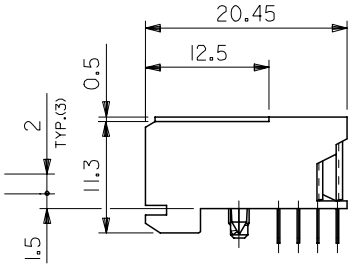
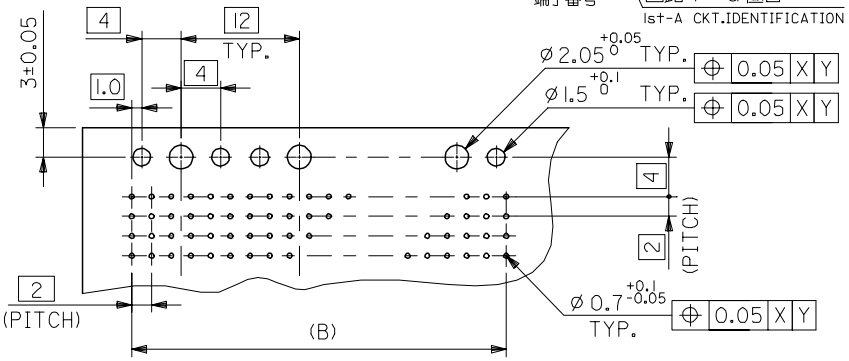
番号 No.	部品 PART NAME	材質 MATERIAL	仕上げ FINISH
①	リセプタクル ハウジング RECEPTACLE HOUSING	液晶ポリマー、ガラス充填、自然色（白）、UL94V-0 LIQUID CRYSTAL POLYMER, GLASS FILLED, NATURAL(WHITE), UL94V-0	— // —
②	リセプタクル ターミナル RECEPTACLE TERMINAL	リン青銅 PHOSPHOR BRONZE	⚠1.

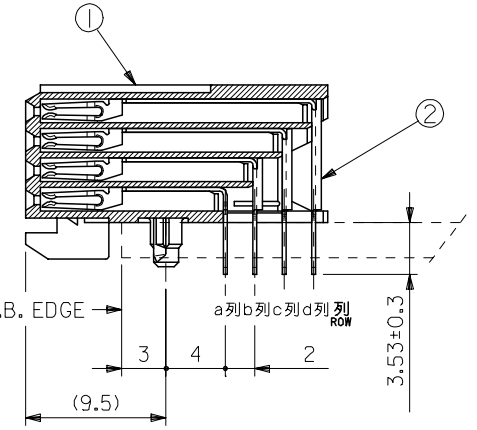








基板穴推奨寸法（部品実装）
RECOMMENDED P.C.B.LAYOUT (COMPONENT SIDE)



A-A
(NON-SCALE)

注記
NOTE :

⚠1. ターミナル めっき仕様
TERMINAL PLATING
金めっき：0.76μm MIN.（接点部）
GOLD : 0.76 μm MIN. (CONTACT AREA)
TIN：1.0~2.5 μm，（半田付け部）
TIN: 1.0~2.5 μm. (SOLDER AREA)
ニッケルメッキ：2.0 μm MIN.（下地めっき）
NICKEL : 2.0 μm MIN. (UNDER PLATING)

2. 推奨基板厚 ：t=2.4mm
RECOMMENDED P.C.B. THICKNESS : t=2.4mm

3. 適合プラグ：53901-***5, 55222-***5, 55089-***5
APPLICABLE PLUG :

⚠4. 製品番号及びロットナンバー
MATERIAL NO. & LOT NO.

106	107.98	54867-2169	216
94	95.98	54867-1929	192
58	59.98	54867-1209	120
10	11.98	54867-0249	24
B	A	MATERIAL NO.	PIN

MODIFICATION
EC NO: SD2007/0175
DRWN: Felix Wang 2007/01/11
CHKD: Harvey Wang 2007/01/11
APPR:
DESCRIPTION
REV

QUALITY SYMBOLS
▼=0
Ⓒ▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± ---	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: MM ONLY
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	HWWANG	04/09/26
CHECKED BY	GMA	04/09/27
APPROVED BY	VINCENT	04/09/27

TITLE: MFB B/B CONN 4ROW REC. ASS'Y DIP TYPE (LEAD FREE)

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MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-54867-005
SHEET NO.: 1 OF 1
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

番号 No.	部品 PART NAME	材質 MATERIAL	仕上げ FINISH
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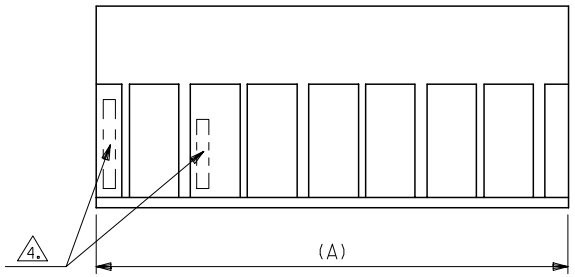

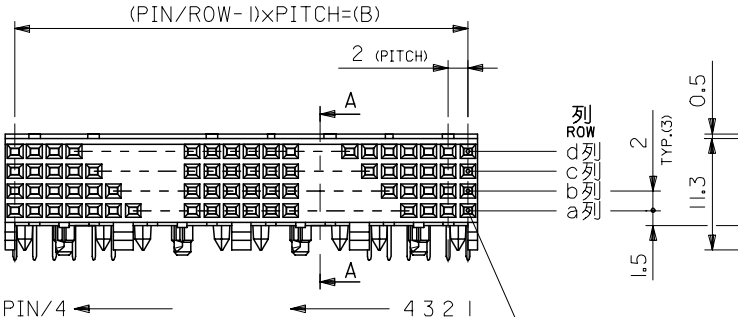

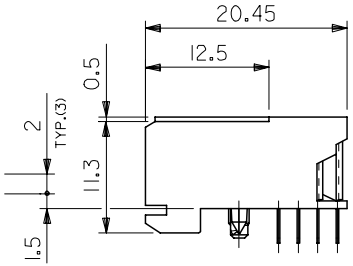

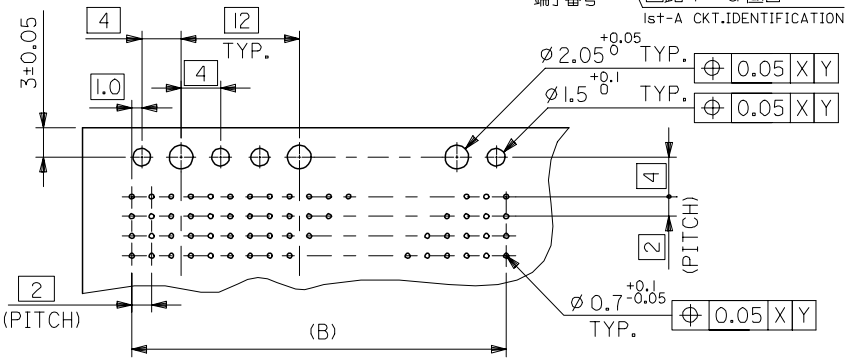

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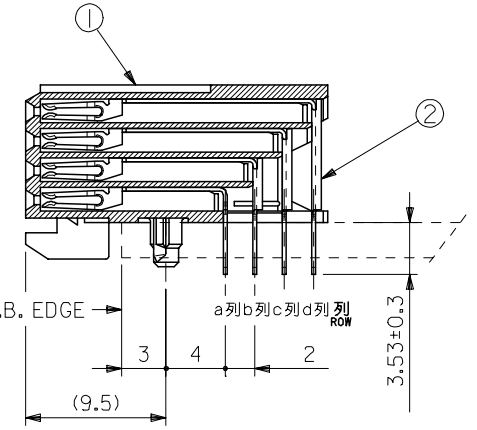

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